TOSHIBA TLGC160

#### TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

# **TLGC160**

#### PANEL CIRCUIT INDICATOR

Unit in mm

- Striking Bright
- All Plastic Mold Type: Clear Transparent Lens
- Low Drive Current, High Intensity Green Light Emission. Recommended Forward Current: IF=15~20mA (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.

### MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	${ m I_F}$	40	mA
Reverse Voltage	$ m V_{R}$	4	V
Power Dissipation	$P_{\mathbf{D}}$	120	mW
Operating Temperature Range	$T_{ m opr}$	-20~85	°C
Storage Temperature Range	$\mathrm{T_{stg}}$	-30~100	$^{\circ}\mathrm{C}$

0.7MAX. 0.45 0.45 0.45 0.45 0.45 0.45
1. ANODE 2. CATHODE
JEDEC —
EIAJ —
TOSHIBA 4-3E1A

OSHIBA 4-3E1A

Weight: 0.12g

#### ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Volta	age	$ m V_{f F}$	$I_{ m F}\!=\!20{ m mA}$	_	2.15	2.8	V
Reverce Current		$I_{\mathbf{R}}$	$V_R = 4V$	_	_	5	$\mu$ A
Luminous Intensity	TLGC160			47	150	_	
	TLGC160 (MN)	$I_{ m V}$	I <sub>F</sub> =20mA (Note)	47.6	_	230	mcd
	TLGC160 (NP)			85.0	_	414	]
Peak Emission Wave Length		$\lambda_{\mathbf{p}}$	$I_{ m F}\!=\!20{ m mA}$		567	_	nm
Spectral Line Half Width		Δλ	$I_{ m F}\!=\!20{ m mA}$	_	25	_	nm

(Note) Rank selection carried out under next standard range respectively, although it needs ±15% additionary for guaranteed limits.

M: 56-112mcd, N: 100-200mcd, P: 180-360mcd.

Each rank products is classified by package unit, and (MN) includes M and N, (NP) includes N and P.

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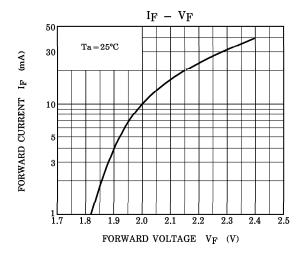
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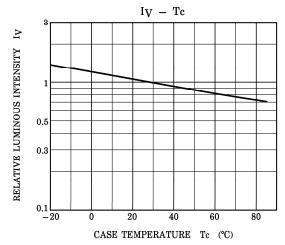
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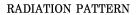
## **PRECAUTION**

Please be careful of the followings.

- Soldering temperature: 260°C MAX. Soldering time: 3s MAX.
   (Soldering portion of lead: up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.







Ta = 25°C

